

Type number	Package	Package description	Total product weight
PDTC123ET	SOT23	TO-236AB	7.70041 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator	
		MSL	PPT	MPPT	MSL	PPT	MPPT				
934054697235	4	1	260	30 s	1	235	20 s	3	Dongguan, China; Seremban, Malaysia; D-22529 HAMBURG, Germany	<div><div></div><div></div></div>	
934054697215	14	1	260	30 s	1	235	20 s	3	Dongguan, China; Seremban, Malaysia; D-22529 HAMBURG, Germany	<div><div></div><div></div></div>	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.08000	100.00000	1.03891
		subTotal		0.08000	100.00000	1.03891
Lead Frame	Iron-nickel alloy	Aluminium (Al)	7429-90-5	0.00229	0.09000	0.02979
		Carbon (C)	7440-44-0	0.00102	0.04000	0.01324
		Chromium (Cr)	7440-47-3	0.00561	0.22000	0.07282
		Cobalt (Co)	7440-48-4	0.01096	0.43000	0.14234
		Iron (Fe)	7439-89-6	1.22301	47.98000	15.88240
		Manganese (Mn)	7439-96-5	0.02192	0.86000	0.28468
		Nickel (Ni)	7440-02-0	0.92121	36.14000	11.96311
		Phosphorus (P)	7723-14-0	0.00051	0.02000	0.00662
		Silicon (Si)	7440-21-3	0.00663	0.26000	0.08607
		Sulphur (S)	7704-34-9	0.00051	0.02000	0.00662
	Pure metal layer	Copper (Cu)	7440-50-8	0.28982	11.37000	3.76371
		Silver (Ag)	7440-22-4	0.06551	2.57000	0.85072
		subTotal		2.54900	100.00000	33.10212
Mould Compound	Additive	Non hazardous	Proprietary	0.14149	2.90000	1.83745
		Triphenylphosphine	603-35-0	0.00244	0.05000	0.03168
	Filler	Silica -amorphous-	7631-86-9	3.51288	72.00000	45.61939
	Pigment	Carbon black	1333-86-4	0.00244	0.05000	0.03168
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.73185	15.00000	9.50404
		Phenol Formaldehyde resin (generic)	9003-35-4	0.48790	10.00000	6.33603
		subTotal		4.87900	100.00000	63.36027
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00002	0.01000	0.00024
		Bismuth (Bi)	7440-69-9	0.00004	0.02000	0.00048
		Iron (Fe)	7439-89-6	0.00002	0.01000	0.00024
		Lead (Pb)	7439-92-1	0.00002	0.01000	0.00024
	Tin solder	Tin (Sn)	7440-31-5	0.18491	99.95000	2.40127
		subTotal		0.18500	100.00000	2.40247
	Pure metal	Copper (Cu)	7440-50-8	0.00741	100.00000	0.09626
Wire		subTotal		0.00741	100.00000	0.09626

**Note(s):**

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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